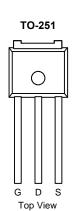


# P-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ)			
- 60	0.053 at V <sub>GS</sub> = - 10 V	- 25	26			
- 00	0.062 at V <sub>GS</sub> = - 4.5 V	- 20	20			



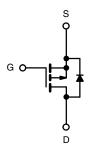
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



#### **APPLICATIONS**

- · High Side Switch for Full Bridge Converter
- DC/DC Converter for LCD Display



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $(T_A = 2)$	25 °C, unless otherw	rise note)			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 60	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	- 25		
Continuous Drain Guiterit (1) = 130 °C)	T <sub>C</sub> = 125 °C	l ' <sup>D</sup> [	- 20	_	
Pulsed Drain Current		I <sub>DM</sub>	- 100	A	
Avalanche Current, Single Pulse		I <sub>AS</sub>	- 22		
Repetitive Avalanche Energy, Single Pulse <sup>a</sup>	L = 0.1 mH		24.2	mJ	
Dower Discinstian	T <sub>C</sub> = 25 °C	P <sub>D</sub>	38.5 <sup>c</sup>	W	
Power Dissipation	T <sub>A</sub> = 25 °C		2.3 <sup>b, c</sup>	l vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian un lumation to Auchionab	t ≤ 10 s	R <sub>thJA</sub>	17	21	°C/W
Maximum Junction-to-Ambient <sup>D</sup>	Steady State	' 'thJA	45	55	
Maximum Junction-to-Case		R <sub>thJC</sub>	2.7	3.25	

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. When mounted on 1" square PCB (FR-4 material).
- c. See SOA curve for voltage derating.
- d. Based up on  $T_C$  = 25 °C.



Parameter	Symbol	Test Conditions	Min . Typ.		Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			- 50	μΑ	
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ} \text{ C}$			- 125		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 10 A		0.053			
Drain Course On State Besistance	Book	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 10 A, T <sub>J</sub> = 125 °C		0.102		Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = -10 \text{ V}, I_D = -10 \text{ A}, T_J = 150 \text{ °C}$	0.120				
		$V_{GS} = -4.5 \text{ V}, I_D = -5 \text{ A}$		0.062			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 10 A		22		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			1140	1710	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		130			
Reverse Transfer Capacitance	C <sub>rss</sub>			90			
Total Gate Charge <sup>c</sup>	$Q_g$			26	40	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -10 \text{ A}$		4.5			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			7		1	
Gate Resistance	R <sub>g</sub>	f = 1 MHz		7		Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	15		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -30 \text{ V, R}_{L} = 3 \Omega$		9	15		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong -19 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		65	100	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			30	45		
Drain-Source Body Diode and Charact	eristics (T <sub>C</sub> = 2	5 °C) <sup>b</sup>		•			
Continuous Current	Is				- 30		
Pulsed Current	I <sub>SM</sub>				- 30	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = - 19 A, V <sub>GS</sub> = 0 V		- 1	- 1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = - 19 A, di/dt = 100 A/μs		41	61	ns	

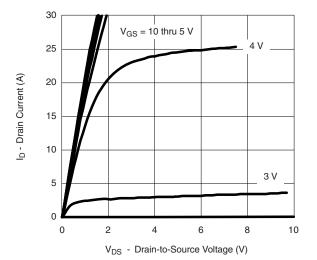
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

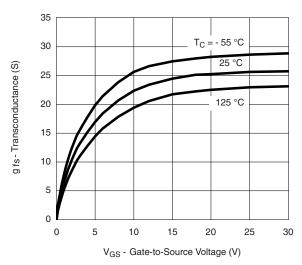
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



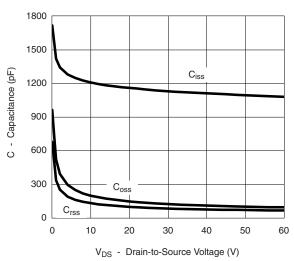
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



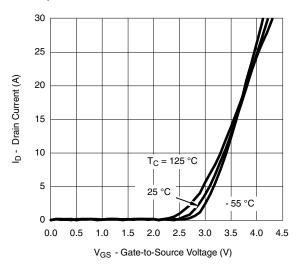
#### **Output Characteristics**



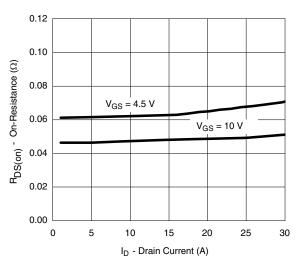
#### Transconductance



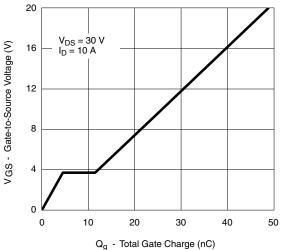
Capacitance



#### Transfer Characteristics



#### On-Resistance vs. Drain Current

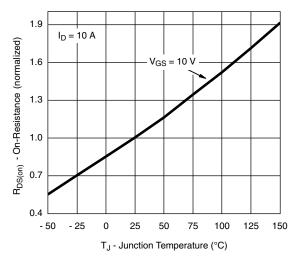


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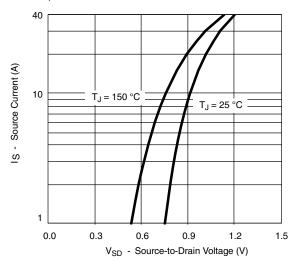
Gate Charge



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

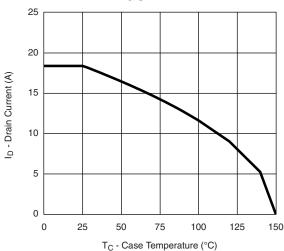


On-Resistance vs. Junction Temperature

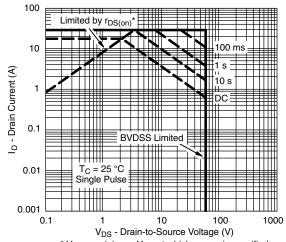


Source-Drain Diode Forward Voltage

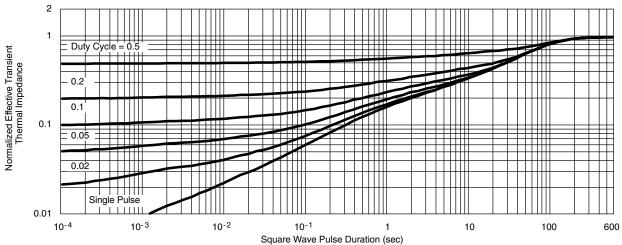
#### **THERMAL RATINGS**



Maximum Drain Current vs. Case Temperature



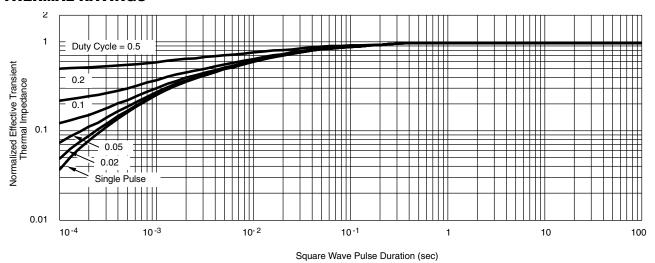
\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which r<sub>DS(on)</sub> is specified **Safe Operating Area** 



Normalized Thermal Transient Impedance, Junction-to-Ambient



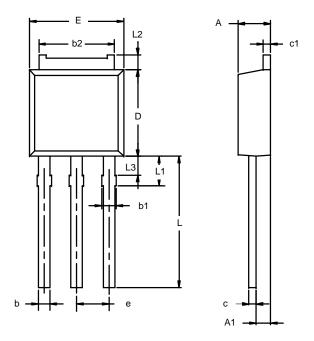
#### **THERMAL RATINGS**



Normalized Thermal Transient Impedance, Junction-to-Case



### **TO-251AA**



Note: Dimension L3 is for reference only.

	MILLIN	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
<b>A</b> 1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090	BSC	
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	



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